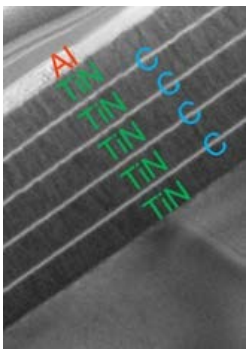
Nano-heat seminar

Modeling and characterization of micro and nanostructures



Heat transfer in electronic packaging, and particularly at the nanoscale, is one of the major challenges facing modern and future systems. Understanding the fundamental transport physics, limitations and interactions at the nanoscale and properties of materials with extremely high thermal conductivity is the topic of his seminar.

Registration deadline: November 14th, 2013

https://ime.wufoo.com/forms/registration-for-nanoheat-seminar/

The seminar is open and free of charge. All travel expenses are covered for the PhD candidates and thesis advisors in the Nano-Network, and travel expense reimbursements will be given after the seminar.

When:
December 09, 2013
09:00 – 15:30

Where:
SINTEF MiNaLab

Gaustadalleen 23 C
Oslo

Topics and invited speakers

Electrothermal characterization of nanostructured thermal interface materials	M. Barako, Stanford University
Extreme-reduced thermal conductivity of carbon nanocoils	Z. Zhang, NTNU
Thermal management options enabling 3D chip stack scaling	T. Brunschwiler, IBM Research
Ultra fast optical measurements and modeling of nanoscale thermal conduction	A Sood, Stanford University
IR thermometry and novel composites for electronic packaging	S. Lingamneni, Stanford University
Modeling and design of thermoelectric microgenerators - device and packaging considerations	M. Dunham, Stanford University

NanoNetwork
Norwegian PhD Network on Nanotechnology for Microsystems

The Research Council of Norway

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